

Progress in the development of the vertex detector with fine pixel CCD at the ILC

Constantino Calancha Paredes^{*1}, A. Dubey², H. Ikeda³, A. Ishikawa², S. Ito², E. Kato², A. Miyamoto¹, T. Mori², H. Sato⁴, T. Suehara², Y. Sugimoto¹, H. Yamamoto²

High Energy Accelerator Research Organization¹

Tohoku University, Department of Physics²

Institute of Space and Astronautical Science, JAXA³

Shinshu University⁴

E-mail: calancha@post.kek.jp

We are developing the vertex detector with a fine pixel CCD (FPCCD) for the international linear collider (ILC), whose pixel size is $5 \times 5 \mu\text{m}^2$. ILC physics program impose several design requirements, as high granularity and low occupancy. FPCCD also impose several requirements in the readout ASIC, mainly, fast readout speed, low noise and low power consumption as well.

We present the status of the R&D to achieve those design requirements.

*22nd International Workshop on Vertex Detectors
September 15th-20th, 2013
Lake Starnberg, Germany*

^{*}Speaker.

1. Introduction

One of the most important physics that the ILC is aiming to study is the verification of the Higgs mechanism, which is reflected in the Higgs boson couplings. The measurement of these various couplings requires accurate particle identification; in particular, excellent separation between b-quarks and c-quarks, and between light quarks and gluon are crucial. In order to realize ILC's highly efficient flavor tagging, we need a vertex detector with an impact parameter resolution of $5 \oplus 10/(p\beta \sin^{3/2}(\theta))$ (μm) and a low level of pixel occupancy for accurate track reconstruction. To achieve this performance the FPCCD uses a finely segmented pixel with the size of $5 \times 5 \mu\text{m}^2$ and reads out during the intertrain time [1], [2]. FPCCD has several advantages. The finely segmented pixel makes it possible to achieve an impact parameter resolution below $1.4 \mu\text{m}$. The intertrain readout frees us from beam induced RF noise. The $50 \mu\text{m}$ thick sensor indicates small multiple coulomb scattering. Here we will address the performance study results of the readout ASIC for FPCCD vertex detector and its future prospects.

2. FPCCD Detector

Baseline Design Vertex Detector

In order to reach performance level, the ILD vertex detector should comply with the following specifications:

- A spatial resolution near the IP better than $3 \mu\text{m}$
- A material budget below $0.15\% X_0$ /layer
- A first layer located at a radius of $\approx 1.6 \text{ cm}$
- A pixel occupancy not exceeding a few %

The power consumption should be low enough to minimize the material budget of the cooling system inside the detector sensitive volume.

Simulations show that such resolution level is feasible with the proposed technologies (Fig. 1).

The baseline design of the ILD vertex detector consists of three, nearly cylindrical, concentric layers of double-sided ladders. Each ladder is equipped with pixel sensors on both sides, $\approx 2 \text{ mm}$ apart, resulting in six measured impact positions for each charged particle crossing the detector (Fig. 2). The radii covered by the detector range from 16 mm to 60 mm . The material budget of each ladder amounts to $\approx 0.3\% X_0$, equivalent to $0.15\% X_0$ /layer.

This geometry is independent of the actual pixel technology being finally adopted.

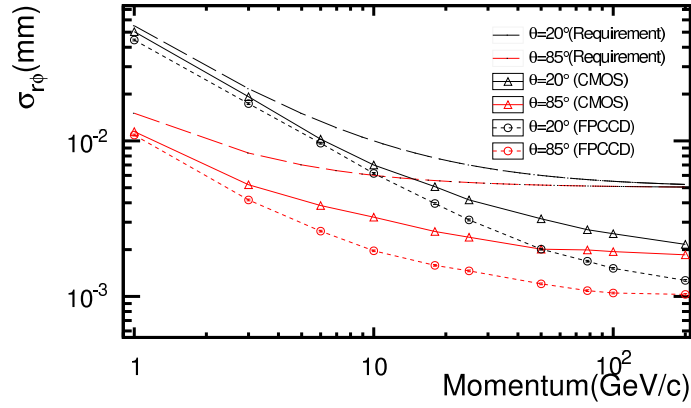


Figure 1: Impact parameter resolution of the ILD vertex detector for two different particle production angles (20° and 85°), assuming the baseline point resolution for the CMOS option (solid line), and the FPCCD option (dotted line). The curves with long dashes show the performance goal.

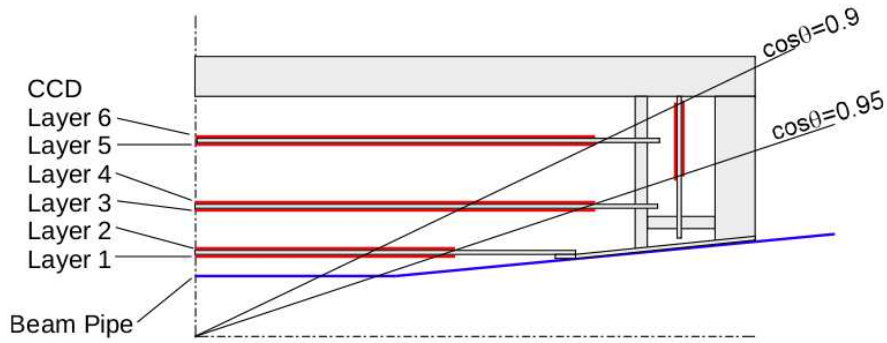


Figure 2: Schematic view of the ILD vertex detector.

FPCCD

The FPCCD concept is based on the following:

1. Very small pixel size ($\approx 5 \mu\text{m}$).
2. Fully depleted sensitive volume with $15 \mu\text{m}$ epitaxial layer thickness.
3. Readout between consecutive inter bunch trains.

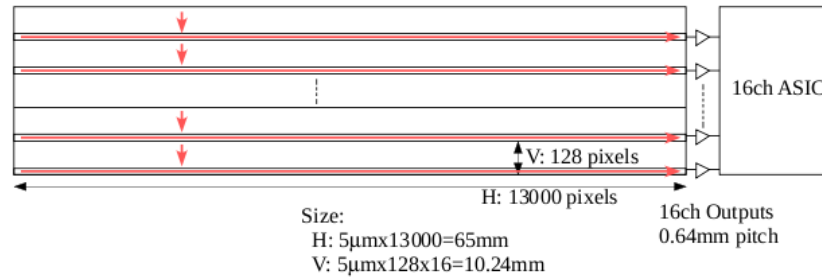


Figure 3: Schematic view of a ladder.

The first item provide FPCCD detector with excellent impact parameter resolution, below $1.4 \mu\text{m}$, and it also reduce the occupancy by beam-related backgrounds. This is particularly important for the inner layers.

The second item imply the charge spread between pixels is very small.

Readout in the intertrain has the additional advantage that the FPCCD is intrinsically free of beam-induced RF noise.

Another advantage of using FPCCD, and an unique feature of this sensor technology, it is use the cluster shapes to the beam-induced backgrounds [3].

CCD is a sort of established technology. CCDs have been used for the vertex detector of SLD detector at the Stanford Linear Collider (SLC) and worked excellently [4]. CCDs with the pixel size smaller than $5 \mu\text{m}$ are widely used for cameras of mobile telephones. FPCCD, therefore, seems a cost-effective technology for future vertex detectors.

Schematic design of the FPCCD sensor is shown in Figure 3. The pixel size is $5 \mu\text{m}$ square and the thickness of the sensitive layer is $15 \mu\text{m}$. For the outer layers, the pixel size could be somewhat larger. Each CCD wafer has 16 outputs covering 16 regions, and each region has $128(V) \times 13000(H)$ pixels. The reason why the number of vertical(V) transfer is much less than the number of horizontal(H) transfer is that this configuration is more advantageous for the radiation tolerance. Each region has a horizontal register to transfer the signal charge to the output node. Pixels in the horizontal registers should be sensitive to the charged particles, as well as standard pixels. The frequency to read out the whole pixels with this configuration is $\approx 10 \text{ Mpixels/s}$.

The output signals from one edge of the CCD wafer are processed by an ASIC located next to the CCD wafer. This ASIC will have functions of amplifier, low-pass filter, correlated double sampler, and analog-to-digital converter (ADC) for 16 channels (Fig. 4).

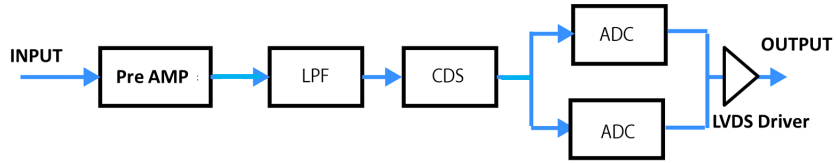


Figure 4: readout ASIC overall architecture

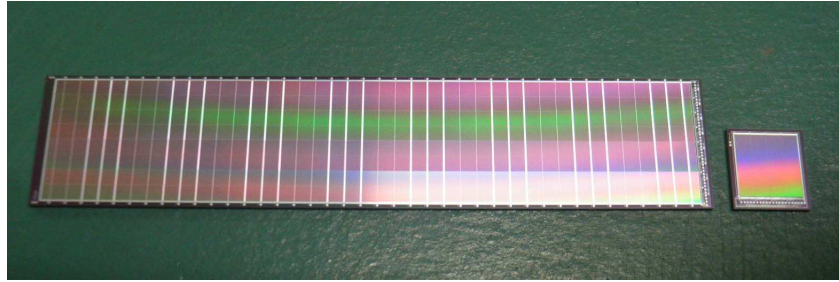


Figure 5: Small and full size prototype sensor with 6 μm pixel size.

3. Status R&D on FPCCD

Small Prototype Tests

We have made small prototype sensors with 6 μm pixel size and full size prototypes for the inner layers (Fig. 5). The readout system has been developed with 3 front-end ASIC'S prototypes already fabricated. The last ASIC prototype matches most of the design requirements [5] when operating at frequencies lower than 50 MHz. At high frequency (100 MHz) it is observed one increase in the noise of the readout system. Figure 6 shows the sensor response when irradiated with Fe^{55} . The signal peak is visible around 59 ADC.

Software R&D

We have developed a new vertex tracking, FPCCD Track Finder [6].

The new track finder tracking efficiency is $\approx 99\%$ for $P_T > 0.6 \text{ GeV}/c$. Figure 7 shows the improve in the tracking efficiency for low P_T tracks when using FPCCD.

We have found that using a bigger pixel size (10 μm) in the outer layers saves $\approx 30\%$ power consumption with no impact on the performance [6].

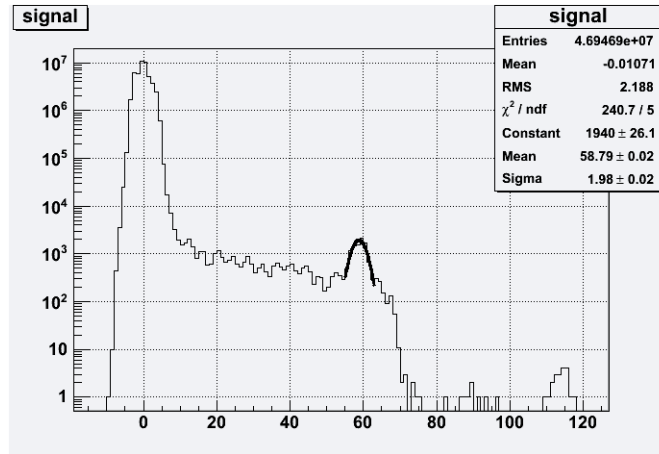


Figure 6: Fe55 peak.

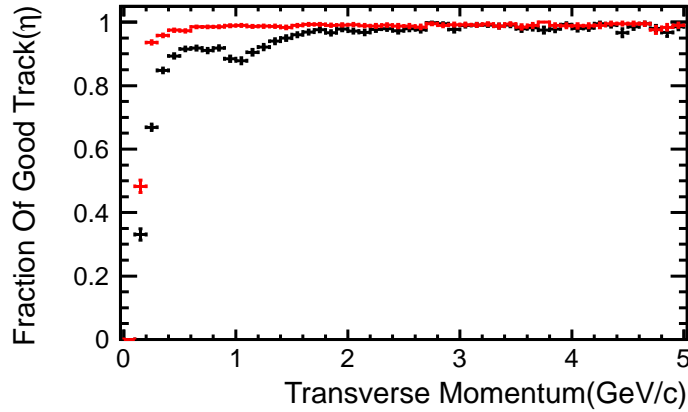


Figure 7: Comparison FPCCD Track Finder (red) with previous vertex tracking [7] (black).

4. Conclusion

Fine pixel CCD (FPCCD) is one of the three sensor technologies being actively developed for the ILC vertex detector. We have covered the status of the R&D in the FPCCD detector. The tests carried out on the small prototypes match the design requirements on noise level and power consumption at low frequency (< 50 MHz).

We have developed a new Silicon Tracking, FPCCD Track Finder, which improves tracking efficiency on low P_T tracks.

We have found that using pixel sizes of $10 \mu\text{m}^2$ in the outer layers reduce 30% the power consumption while keeping similar d_0 resolution and occupancy.

We are analyzing the Charge Transfer Inefficiency (CTI) for the FPCCD. We plan to perform a beam test to study the radiation hardness of the sensors.

References

- [1] Y. Sugimoto, et al., *CCD-based vertex detector for GLC*, *Nucl. Instrum. Meth.* **A549** , 87-92, 2005.
- [2] Y. Sugimoto, *Fine Pixel CCD Option for the ILC Vertex Detector*, *Proceedings of International Linear Collider Workshop*, Stanford, California, 18-22 Mar. 2005, 550-554.
- [3] Y. Sugimoto, et al., *FPCCD Vertex Detector R&D for ILC*, [[arXiv:1202.5832 physics.ins-det](#)]
- [4] K. Abe, et al., *Nucl. Instrum. Meth.* **A400** (1997) 287.
- [5] E. Kato, et al., *Development of readout ASIC for FPCCD vertex detector at the ILC*, [<http://ieeexplore.ieee.org/xpl/articleDetails.jsp?arnumber=6551171>]
- [6] *Performance Evaluation and Software Development of FPCCD Vertex Detector in ILC, ECFA LC2013*.
- [7] T. Behnke, J. E. Brau, P. N. Burrows, J. Fuster, M. Peskin, et al., *The International Linear Collider Technical Design Report Volume 4: Detectors*, [[arXiv:1306.6329 physics.ins-det](#)].